


MATERIAL DECLARATION SHEET



Material Number	PTVS10-076C-SH			
Product Line	Semiconductor products			
Compliance Date	February 1 st 2014			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.	Material Weight (g)
1	Encapsulation	Epoxy Resin	0.598000	Bisphenol Epoxy Resin	1675-54-3	40.00	5.23	13.07	0.239
				Epoxy Resin	25085-99-8	20.00	2.61		0.120
				Crystalline Silica	14464-46-1	23.00	3.01		0.138
				Brominated Epoxy Resin	40039-93-8	12.00	1.57		0.072
				Iron Oxide	51274-00-1	2.00	0.26		0.012
				Titanium Oxide	13463-67-7	3.00	0.39		0.018
2	Electrodes	Copper	2.374743	Copper	7440-50-8	99.10	51.43	51.90	2.353
				Silver	7440-22-4	0.40	0.21		0.009
				Misc not to declare	-	0.50	0.26		0.012
3	Terminations	Copper	1.094389	Copper	7440-50-8	99.50	23.80	23.92	1.089
				Misc not to declare	-	0.50	0.12		0.005
4	Termination Finish	Silver	0.015494	Silver	7440-22-4	100.00	0.34	0.34	0.015
5	Chip	Silicon Die	0.220870	Silicon	7440-21-3	85.74	4.14	4.83	0.189
				Aluminium	7429-90-5	4.99	0.24		0.011
				Nickel	7440-02-0	8.84	0.43		0.020
				Gold	7440-57-5	0.43	0.02		0.001
6	Die Attach	Solder	0.155131	Lead	7439-92-1	92.50	3.14	3.39	0.143
				Tin	7440-31-5	5.00	0.17		0.008
				Silver	7440-22-4	2.50	0.08		0.004
7	Die Coating	Silicone	0.117261	Polysiloxane	63148-62-9	22.11	0.57	2.56	0.026
				Chromium Sesquioxide	1308-38-9	5.67	0.15		0.007
				Fumed Silica	112945-52-5	11.11	0.28		0.013
				Filler	trade secret	61.11	1.57		0.072
		Total Weight	4.575887						